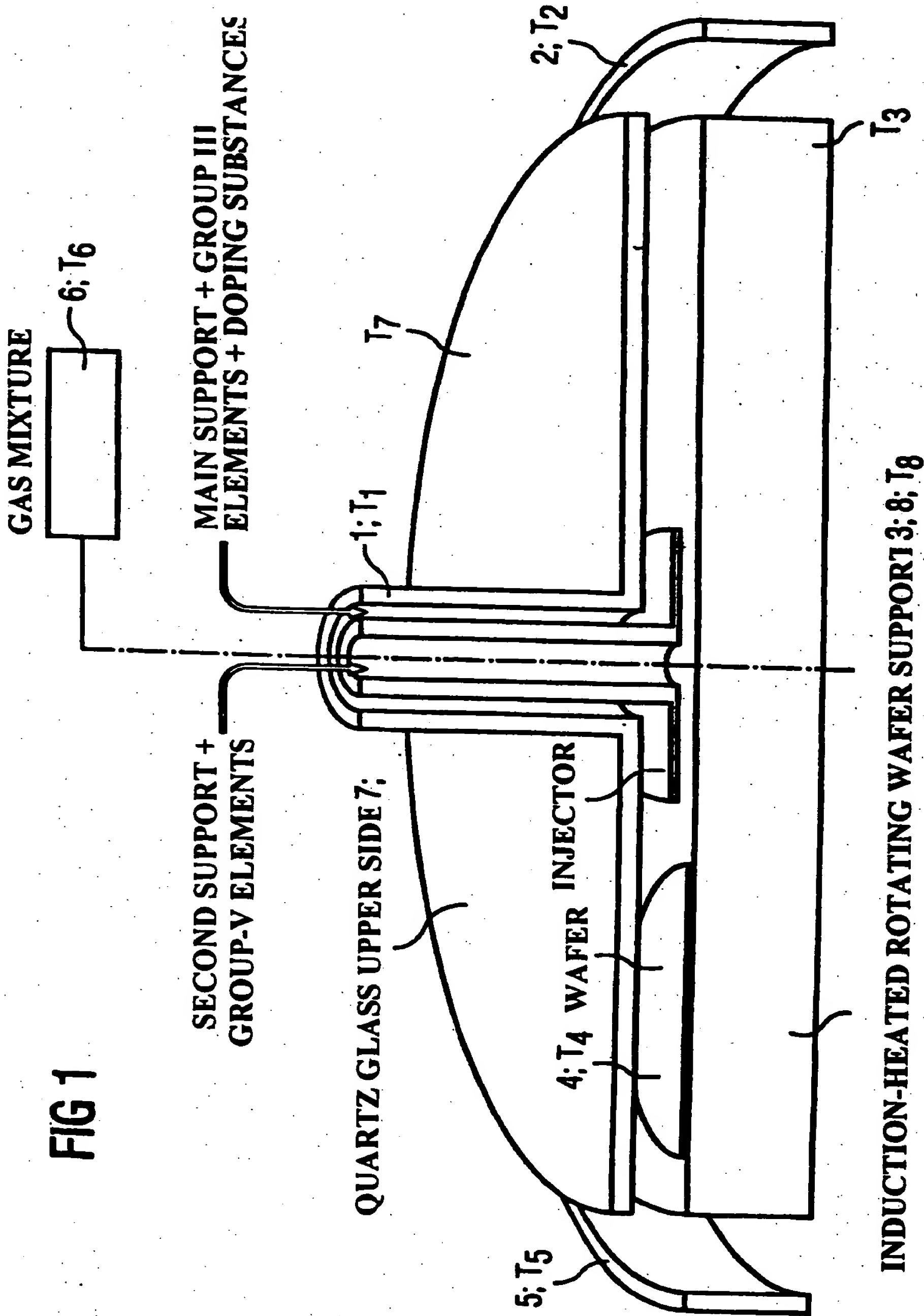




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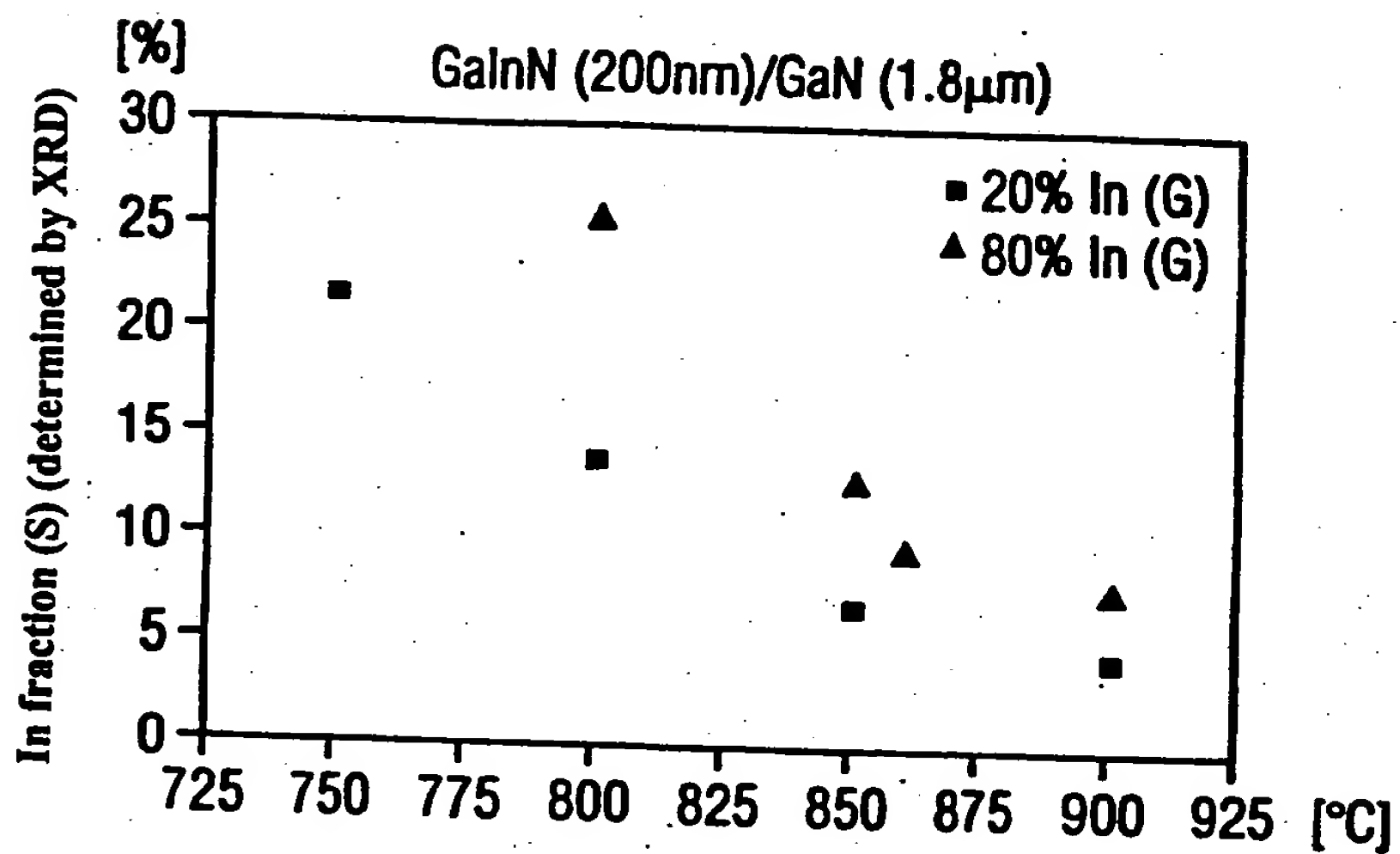


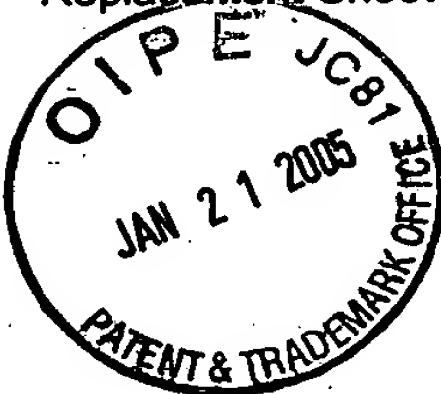


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## FIG 2

In fraction as a function of the production temperature



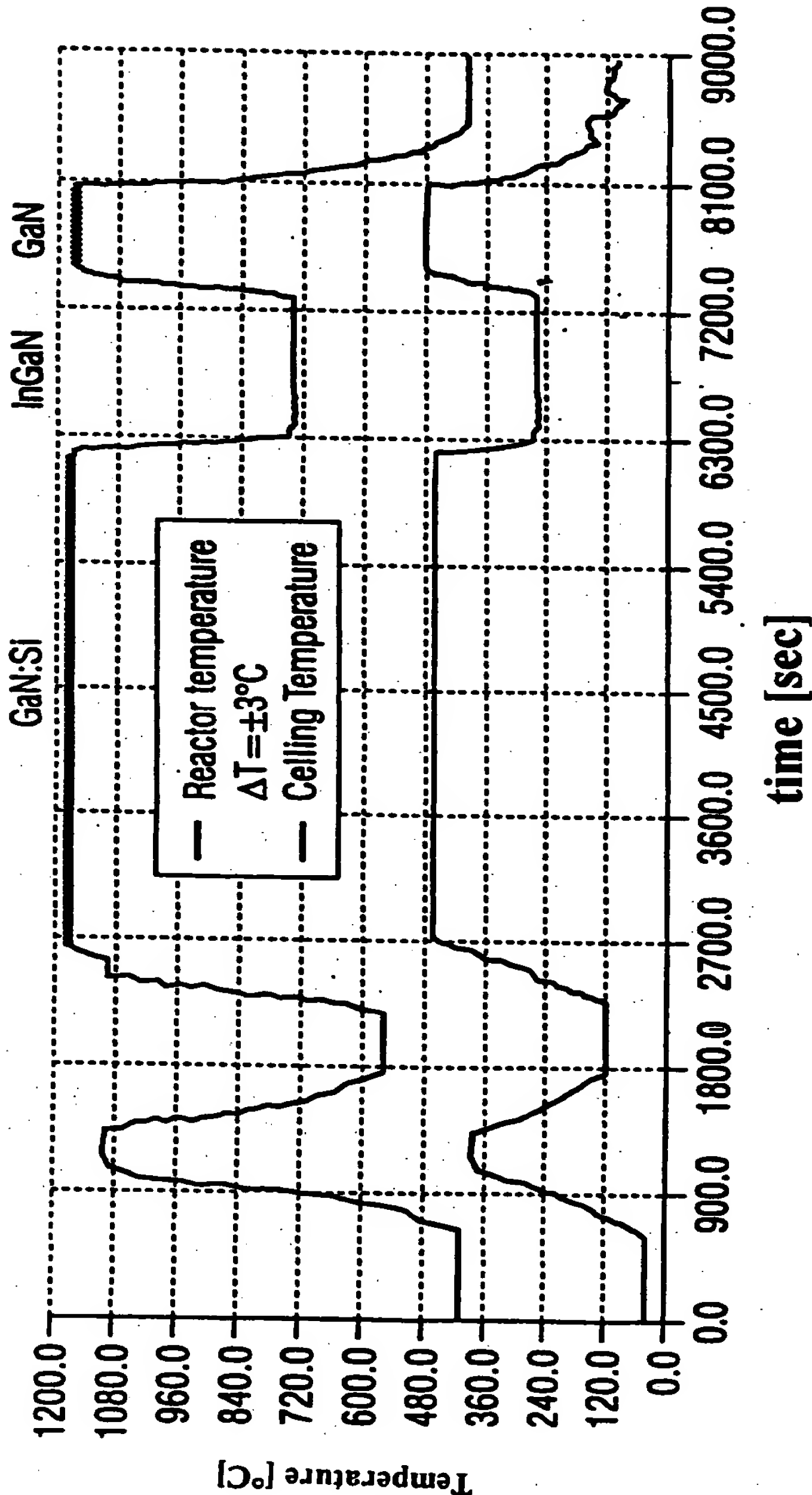


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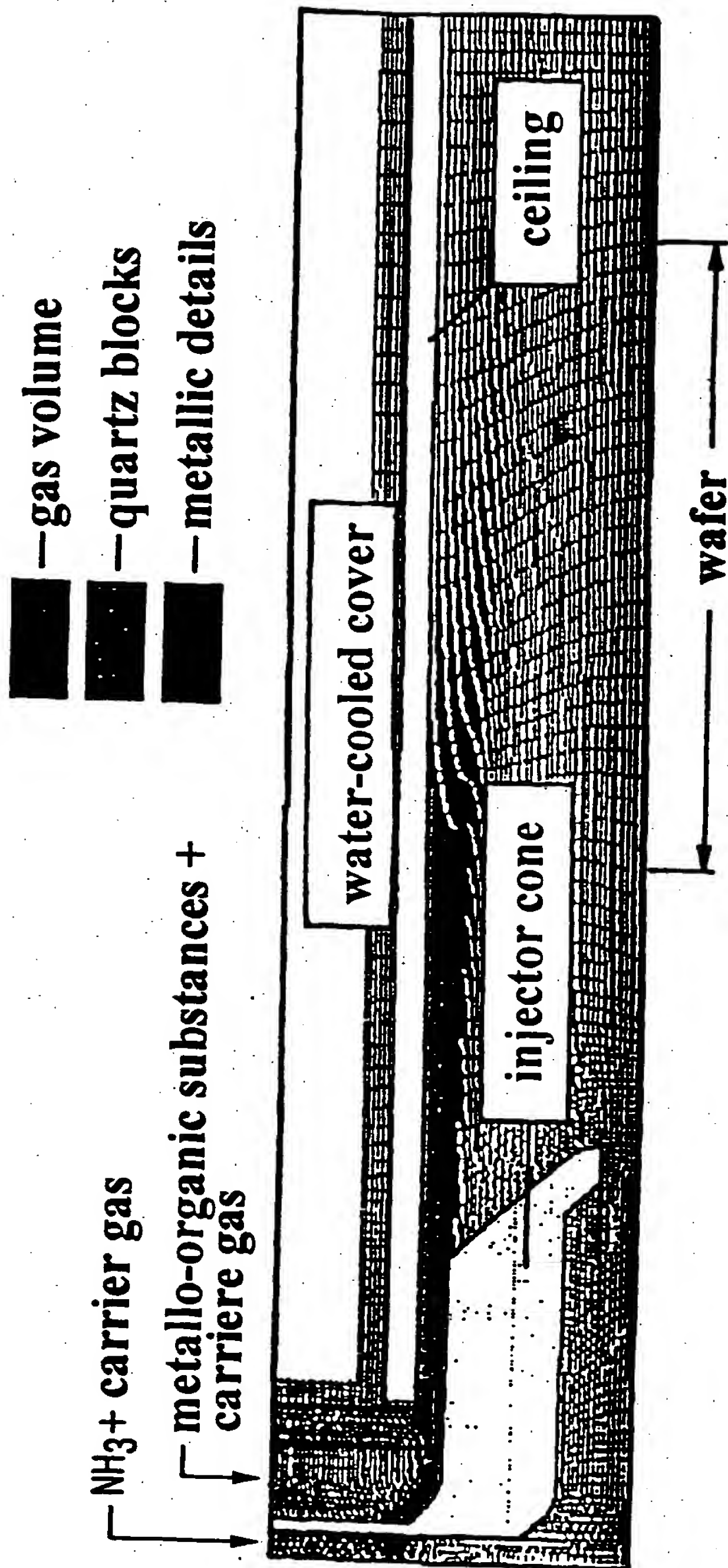
# LOG data of the AIXTRON MOVPE system

## InGaN/GaN DH structure

FIG 3



**Mass Transfer Model**  
**Schematic illustration the computing range and the**  
**finite volume lattice for analysing the mass transfer**  
**FIG 3a**





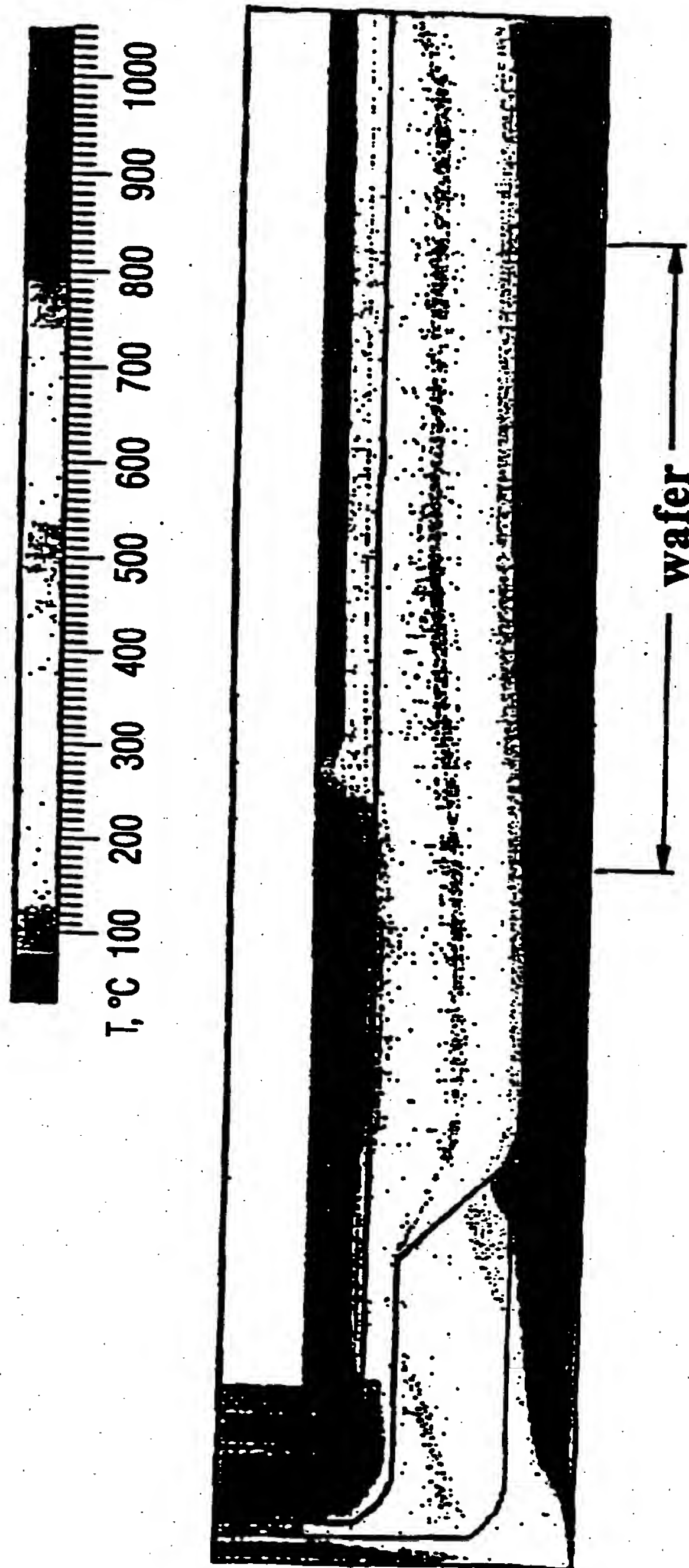
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## Temperature Distribution

The model explains:

- mixture and reaction of precursor flows
- grey diffuse radiation
- conjugated heat transmission

FIG 3b



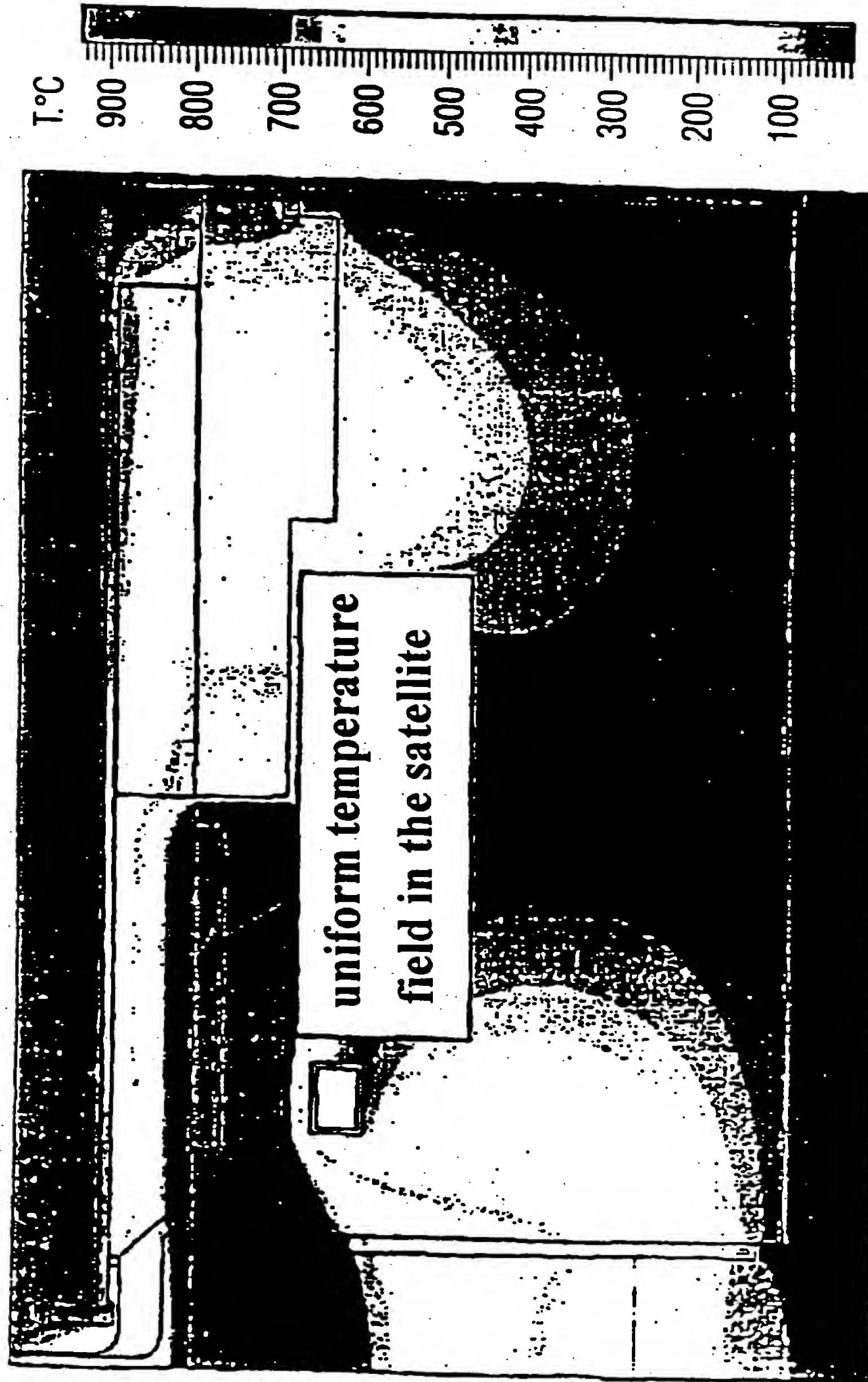


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Detailed Thermal Model  
Temperature Distribution

FIG 3c

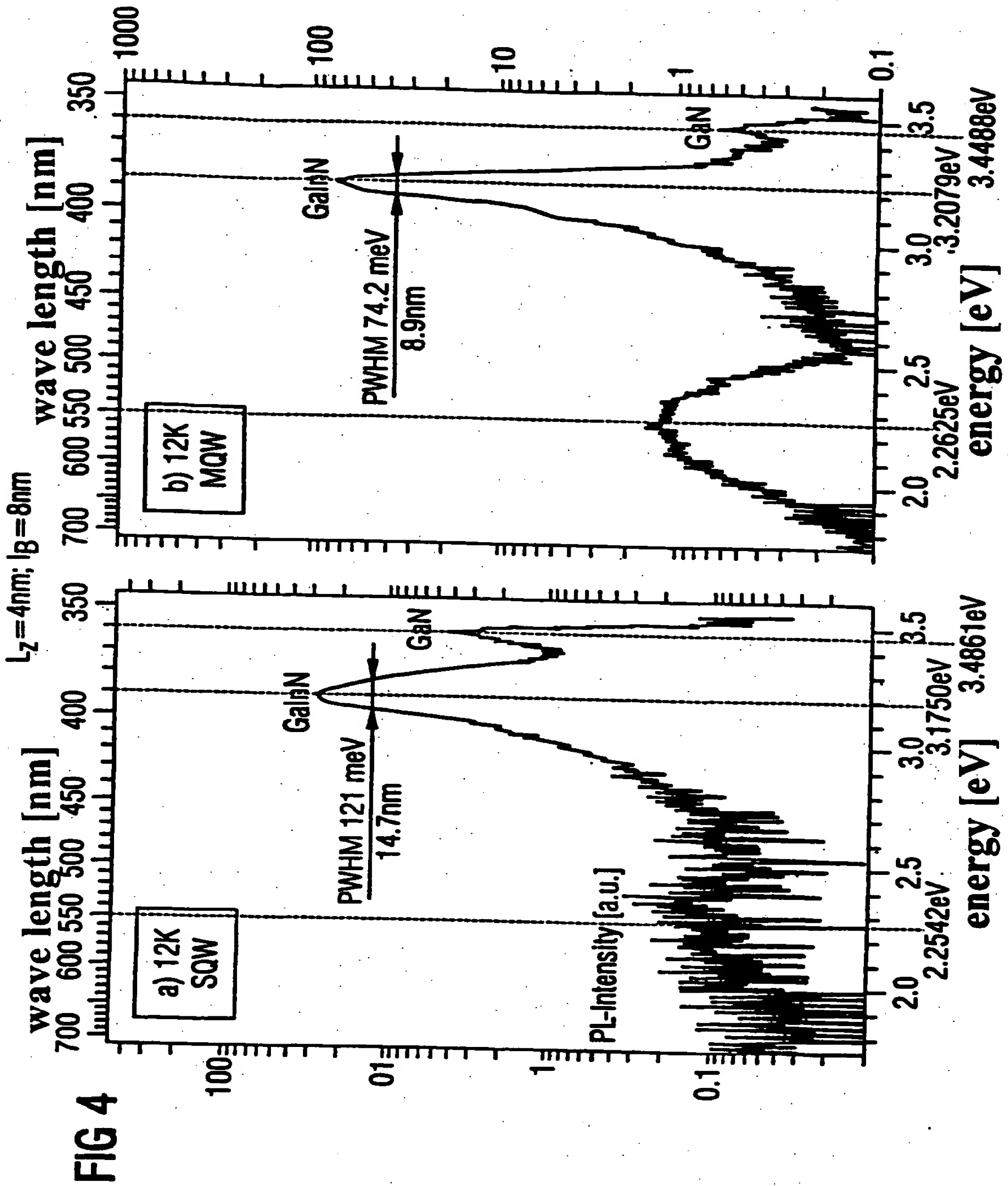
Total output 14 KW; cooling-gas mixture 50% $H_2$ +50% $N_2$



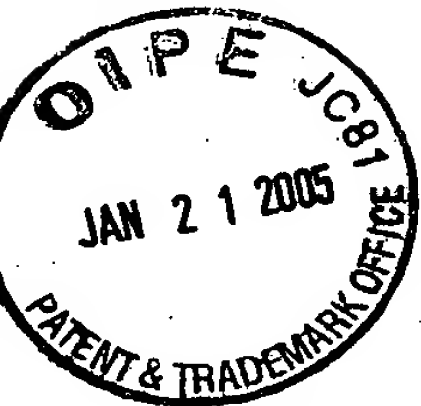


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# LT(12K)PL of SQW and MQW structures







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# Uniformity of InGaN production in a multiple-wafer reaction chamber

Production in AIX 2000HT, wafer size: 7 x 2"

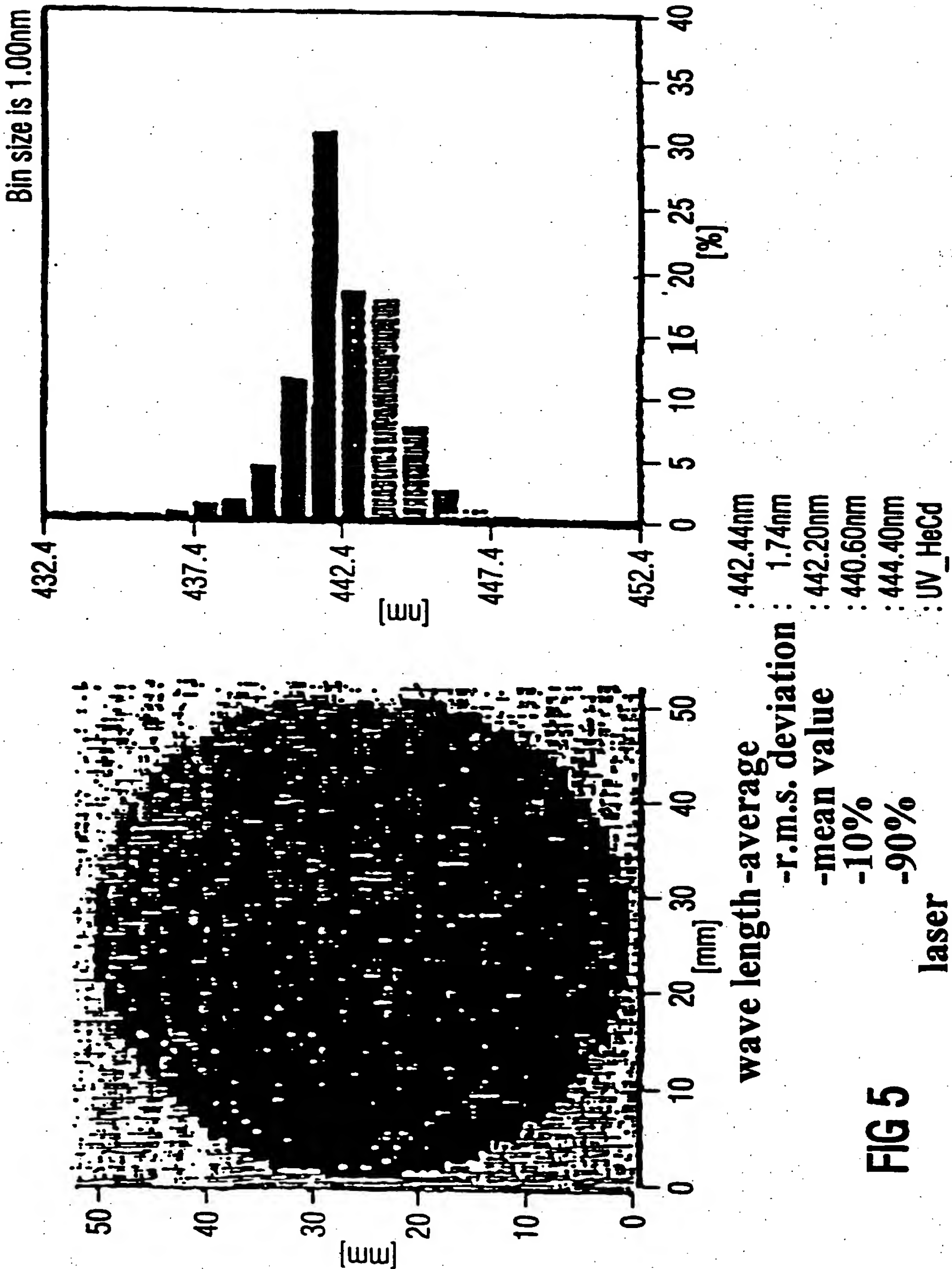
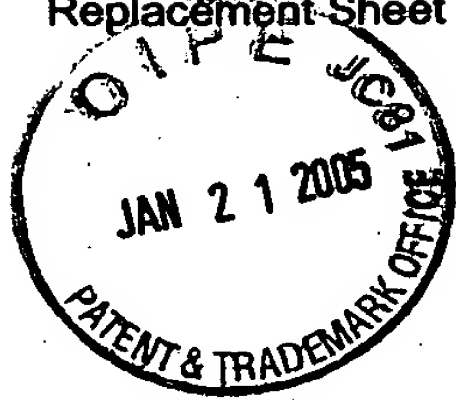


FIG 5

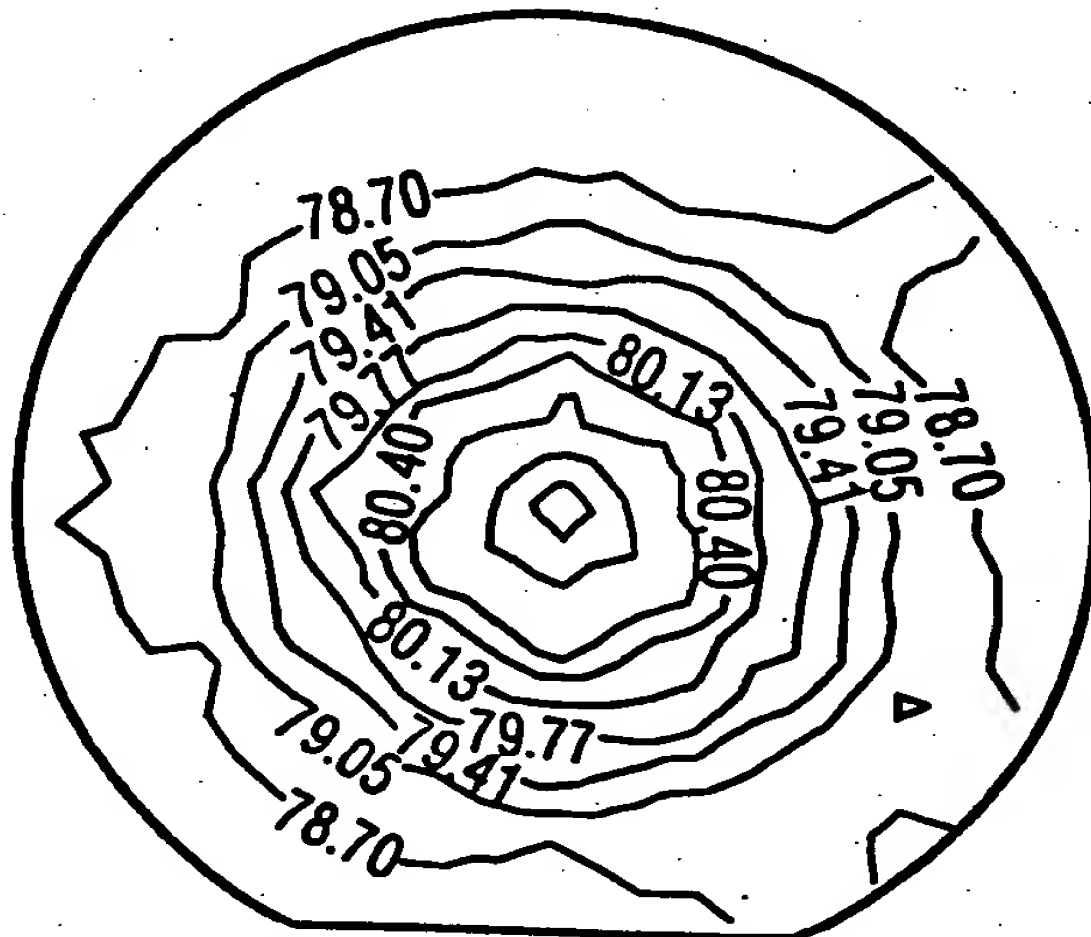




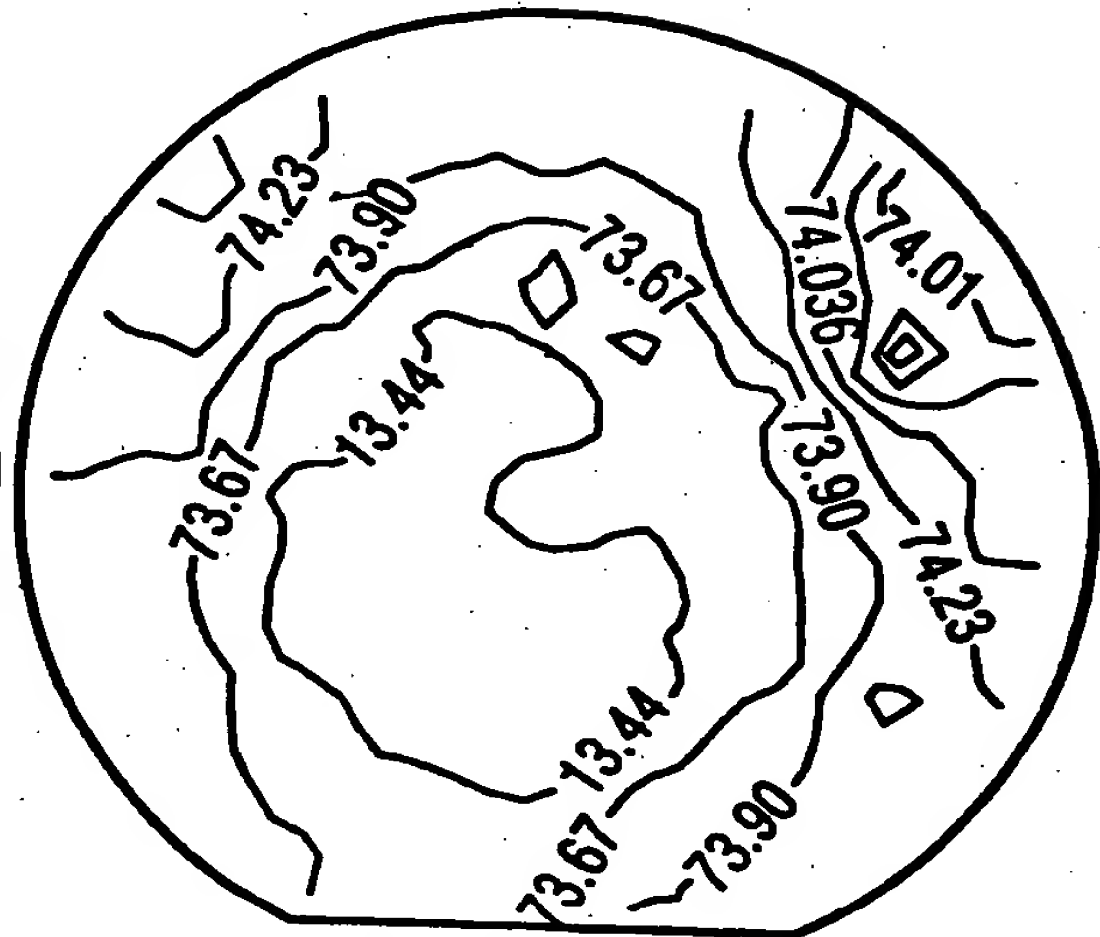
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**FIG 6**

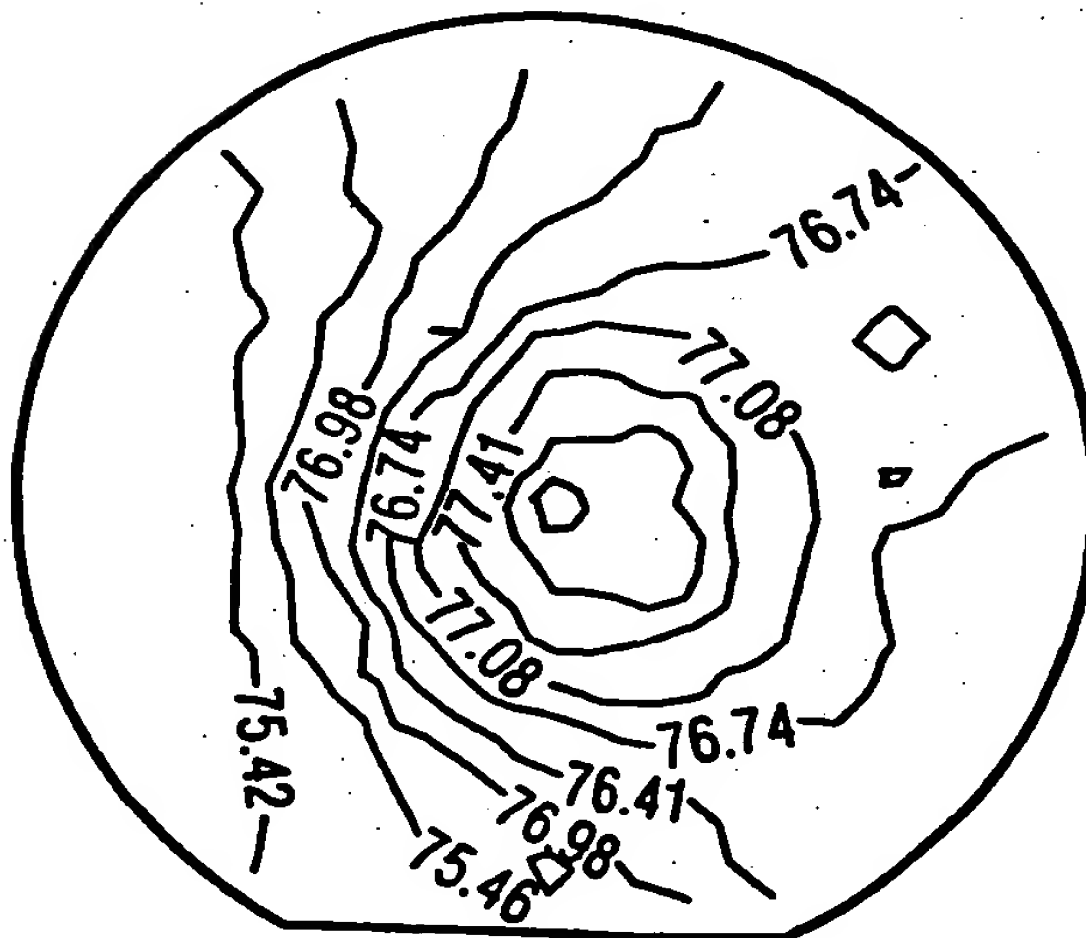
**Wafer-to-wafer homogeneity of n-doped  
GaN/InGaN-DHS**



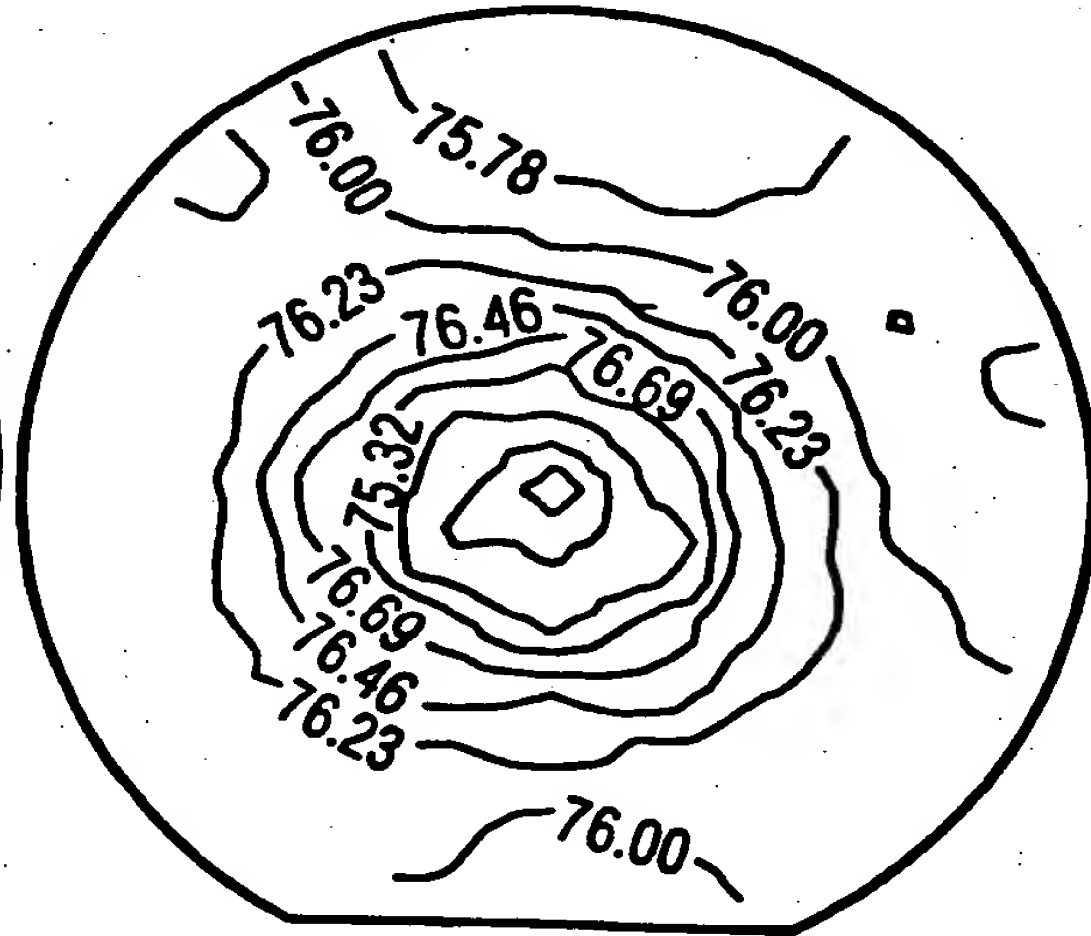
av. value: 79.2 ohm/sq  
std. dev. 1.19%



av. value: 73.8 ohm/sq  
std. dev. 0.61%



av. value: 76.4 ohm/sq  
std. dev. 1.10%



av. value: 76.2 ohm/sq  
std. dev. 0.68%

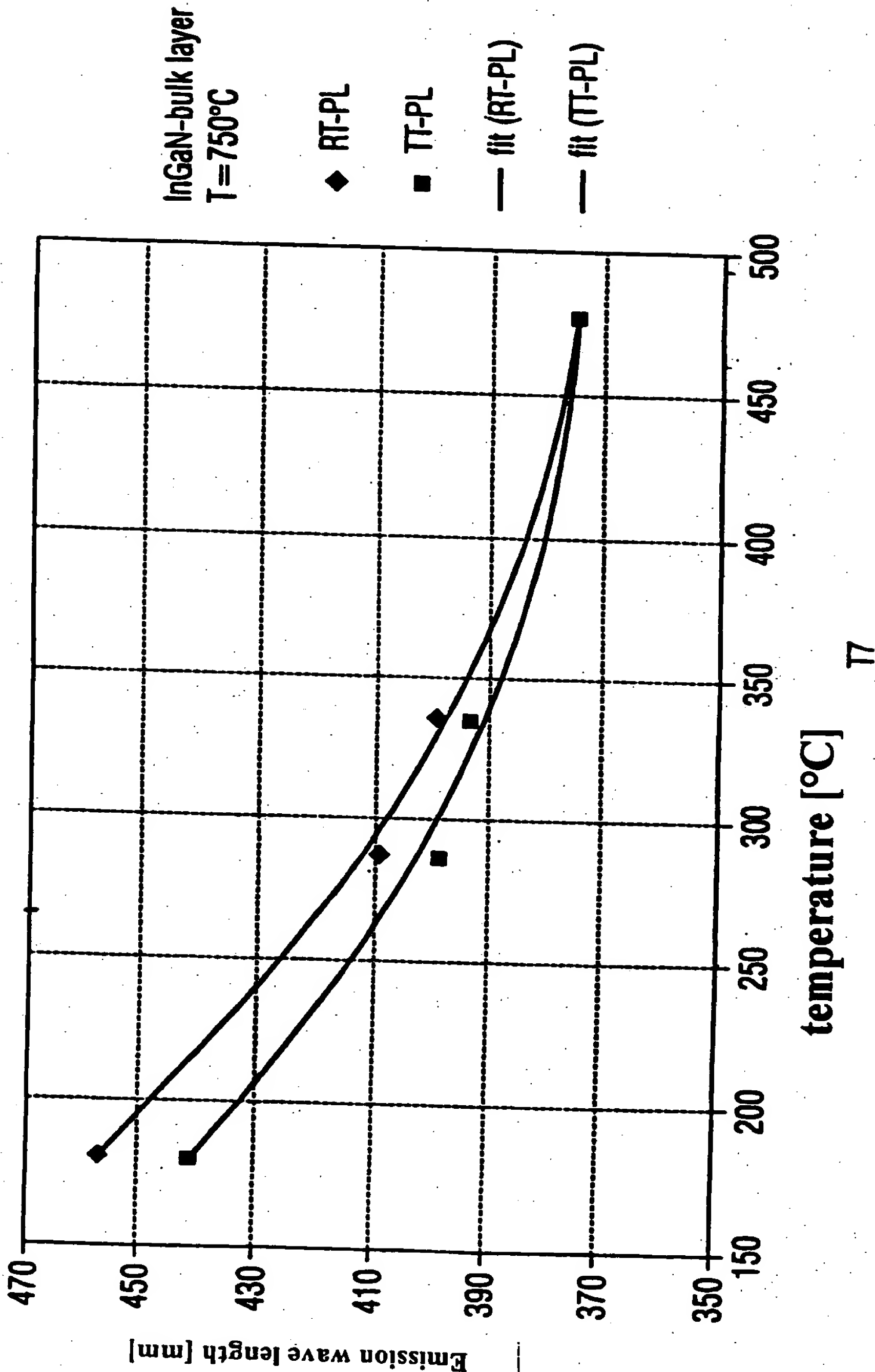
**Wafer-to-wafer r.m.s. deviation: 2,7%**



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Incorporation as a function of the temperature  
of the upper side of the reaction chamber

FIG 7



- reaction chamber underside T9
- reaction chamber injector T1
- reaction chamber ring T2
- reaction chamber upper side T7
- RF coil T8

